

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (Withdrawn): A semiconductor substrate jig used for arranging a film on one surface of a semiconductor substrate, wherein said semiconductor substrate jig comprises:

a frame;

and an expandable member arranged within said frame, and increasing or decreasing volume while deforming a shape of said expandable member by being supplied with fluid therein;

wherein said shape is deformed so that said film arranged between said semiconductor substrate and said expandable member is pressed against said semiconductor substrate as contacting portion of the expandable member to the film is enlarged outwardly from the center of said film as said volume increases.

Claim 2 (Withdrawn): A semiconductor substrate jig as claimed in claim 1, wherein a movable plate is provided inside said expandable member, and is movable to a position contacting said expandable member when said expandable member presses substantially an entire surface of said film against said semiconductor substrate, wherein a state in which said expandable member presses said substantially entire surface of said film to said semiconductor substrate is maintained by said movable plate.

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Claim 3 (Withdrawn): A semiconductor substrate jig claimed in claim 2, wherein a suction mechanism for suctioning said expandable member is provided in said movable plate.

Claim 4 (Withdrawn): A semiconductor substrate jig used for arranging a film on a semiconductor substrate, wherein said semiconductor substrate jig comprises:

a frame with a bottom;

a set of plural annular members arranged concentrically within said frame and constructed so as to be individually movable in a direction perpendicular to said semiconductor substrate, heights of said annular members in said direction perpendicular to said semiconductor substrate gradually increases from an outer circumference toward an inner circumference;

a biasing member for biasing each of said annular members toward said bottom of said frame; and

an operating member contacting said annular members by operating movement in said frame and provided for biasing in a direction separating said annular members from said bottom of said frame, against bias force of said biasing member;

wherein each of said annular members moves so as to gradually press and move said film arranged between said semiconductor substrate and said set of annular members toward said semiconductor substrate from center outward with said operating movement of said operating member.

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5. (Currently amended): A semiconductor substrate jig used in arranging a film to a semiconductor substrate, wherein said semiconductor substrate jig comprises:

a frame;

a set table arranged within said frame;

a porous member plate arranged within said frame ~~so as to be opposite said film on said set table;~~

a floor within said frame spaced from said set table on a side opposite said porous plate;

a rubber film enclosing said set table and porous plate; and

a vacuum hole ~~an air joint~~ formed in said frame, ~~passing through said floor and said set table,~~  
and provided for applying ~~negative~~ pressure to said porous ~~member plate within said rubber film.~~

Claim 6 (Withdrawn): A semiconductor substrate jig comprising:

a first jig having a first suction mechanism sucking said semiconductor substrate; and

a second jig having a second suction mechanism sucking said semiconductor substrate, said first and second jigs being removably constructed and independently sucking said semiconductor substrate.

Claim 7 (New): The semiconductor substrate jig as defined in Claim 5, including a further

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vacuum hole passing through said floor and contacting an outside surface of said film.

Claim 8 (New): The semiconductor substrate jig as defined in Claim 5, including guide shafts passing through said floor and through a wall of said film, movably journaled therewith and arranged to elevate said set table relative to said floor.

Claim 9 (New): A semiconductor substrate jig as defined in Claim 5, including guide shafts passing through said floor and through a wall of said rubber film, movably journaled therewith and arranged to elevate said set table relative to said floor.